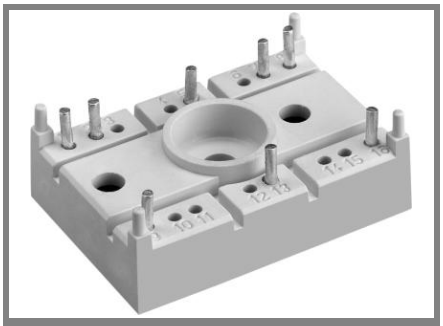
SK 40 GB 123



SEMITOP® 2

Fast IGBT Module

SK 40 GB 123

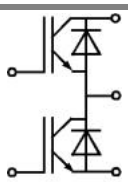
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N-channel homogeneous silicon structure (NPT-Non punch-through IGBT)
- Low tail current with low temperature dependence

Typical Applications

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS



GB

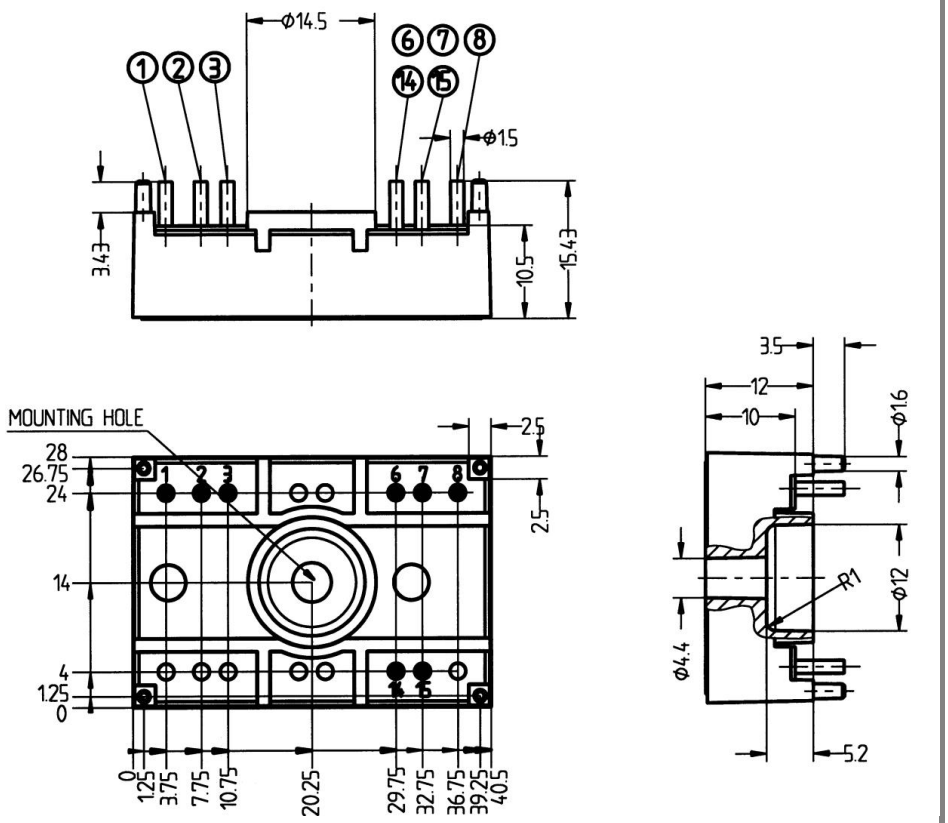
Absolute Maximum Ratings		T_s = 25 °C, unless otherwise specified	
Symbol	**Conditions**	**Values**	**Units**
IGBT			
V_{CES}		1200	V
V_{GES}		± 20	V
I_C	T_s = 25 (80) °C;	40 (27)	A
I_{CM}	t_p < 1 ms; T_s = 25 (80) °C;	80 (54)	A
T_j		- 40 ... + 150	°C
Inverse / Freewheeling CAL diode			
I_F = - I_C	T_s = 25 (80) °C;	48 (34)	A
I_{FM} = - I_{CM}	t_p < 1 ms; T_s = 25 (80) °C;	96 (68)	A
T_j		- 40 ... + 150	°C
T_{stg}		- 40 ... + 125	°C
T_{sol}	Terminals, 10 s	260	°C
V_{isol}	AC 50 Hz, r.m.s. 1 min. / 1 s	2500 / 3000	V

Characteristics		T_s = 25 °C, unless otherwise specified			
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
IGBT					
$V_{CE(sat)}$	I_C = 30 A, T_j = 25 (125) °C		2,5 (3,1)	3 (3,7)	V
$V_{GE(th)}$	V_{CE} = V_{GE}; I_C = 0,0012 A	4,5	5,5	6,5	V
C_{ies}	V_{CE} = 25 V; V_{GE} = 0 V; 1 MHz		2		nF
$R_{th(j-s)}$	per IGBT			0,85	K/W
	per module				K/W
	under following conditions:				
$t_{d(on)}$	V_{CC} = 600 V , V_{GE} = ± 15 V		35		ns
t_r	I_C = 30 A, T_j = 125 °C		45		ns
$t_{d(off)}$	R_{Gon} = R_{Goff} = 20 Ω		250		ns
t_f			45		ns
E_{on} + E_{off}	Inductive load		3,8		mJ
Inverse / Freewheeling CAL diode					
V_F = V_{EC}	I_F = 30 A; T_j = 25 (125) °C		2 (1,8)		V
$V_{(TO)}$	T_j = (125) °C		(1)	(1,2)	V
r_T	T_j = (125) °C		(53)	(73)	mΩ
$R_{th(j-s)}$				1	K/W
	under following conditions:				
I_{RRM}	I_F = 30 A; V_R = 600 V		32		A
Q_{rr}	dI_F/dt = -400 A/µs		5,4		µC
E_{off}	V_{GE} = 0 V; T_j = 125 °C		1,2		mJ
Mechanical data					
M1	mounting torque			2	Nm
w			21		g
Case	SEMITOP® 2		T 32		

SK 40 GB 123

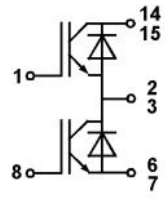
UL Recognized
File no. E 63 532

Dimensions in mm



SUGGESTED HOLEDIAMETER FOR THE SOLDER PINS AND THE MOUNTING PINS IN THE PCB: 2 mm

Case T 32



Case T32 GB

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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